

AMENDMENT TO THE CLAIMS:

The following claim set replaces all prior versions, and listings, of claims in the application:

1. – 14. (cancelled)
15. (previously presented) Process for forming an etched layer in a chip by immersion lithography, the process comprising the sequential steps of:
 - (A) forming a photoresist layer on a substrate wherein the photoresist layer is prepared from a photoresist composition comprising:
 - (a) about 50 to about 99.5 wt% of a binder;
 - (b) about 0 to about 10 wt.% of a photoactive component; and
 - (c) about 0.5 to about 50 wt.% of a fluor containing compound relative to the total of (a)+(b)+(c);
 - (B) imagewise exposing a photoresist layer to form imaged and non-imaged areas,
 - (C) developing the exposed photoresist layer having imaged and non-imaged areas to form the relief image on the substrate,
 - (D) etching the substrate to a predetermined depth, and
 - (E) removing the relief image from the substrate.
16. (previously presented) A process for the production of a chip by immersion lithography, comprising the step of forming a photoresist layer on a substrate, wherein the photoresist layer is prepared from a photoresist composition comprising:
 - (a) about 50 to about 99.5 wt% of a binder;
 - (b) about 0 to about 10 wt.% of a photoactive component; and
 - (c) about 0.5 to about 50 wt.% of a fluor containing compound relative to the total of (a)+(b)+(c).

17. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) a fluor containing compound having a (blocked) acid group, which when unblocked has a pKa < 12.
18. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) a fluor containing compound having two or more acid groups.
19. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) a fluor containing compound having an acid group with a pKa of 9.6 or less
20. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) a fluor containing compound having acid groups which are partly or fully blocked with acid-labile groups
21. (previously presented) Process according to claim 20, wherein the photoresist composition comprises (c) a fluor containing compound having at least partly blocked acid-labile groups, chosen from the group consisting of A) a carbonate formed from a tertiary aliphatic alcohol, B) a tertiary aliphatic or other group which forms a stabilized carbocation, C) an acetal group and D) an orthoester group.
22. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) a fluor containing compound having aromatic groups.
23. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (a) 50 to 99.5 wt% of a polymeric binder

24. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (b) 0 to about 10 wt% photoactive compound
25. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises a binder, which is a polymer comprising acid groups with a pKa < 12
26. (previously presented) Process according to claim 25, wherein the acid groups are partially blocked.
27. (previously presented) Process according to claim 17 wherein the acid group is an hydroxyl group bound to an aromatic group, or a C(CF₃)₂OH bound to an aromatic ring.
28. (previously presented) Process according to claim 17, wherein the acid group is at least partly blocked with a carbonate, acetal group, ortho ester, or tertiary alkyl group.
29. (previously presented) Process according to claim 17, wherein the photoresist composition comprises (a) a binder comprising fluorine groups
30. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (a) a polymer with ring structures
31. (previously presented) Process according to claim 15 or 16, wherein the process is performed at 193 nm.
32. (previously presented) Process according to claim 15 or 16, wherein the photoresist composition comprises (a) an acrylic or methacrylic binder.

33. (new) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) about 1 wt.% to 50 wt.% of the fluor containing compound relative to the total of (a)+(b)+(c).
34. (new) Process according to claim 33, wherein the photoresist composition comprises (c) about 1 wt.% to about 20 wt.% of the fluor containing compound relative to the total of (a)+(b)+(c).
35. (new) Process according to claim 15 or 16, wherein the photoresist composition comprises (c) about 5 wt.% to 50 wt.% of the fluor containing compound relative to the total of (a)+(b)+(c).
36. (new) Process according to claim 35, wherein the photoresist composition comprises (c) about 5 wt.% to about 20 wt.% of the fluor containing compound relative to the total of (a)+(b)+(c).